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INDEX

MA-1: OPENING SESSION

- 1 Microtechnology – the Norwegian perspective (Abstract only) 1
Henrik Jakobsen, VUC, Norway

MP-A1: BUSINESS

- 2 Outsourcing to China 2-17
Michael Pecht, CALCE, USA
- 3 IC Packaging Business and Industry of Taiwan 18-22
*Shen-Li Fu, I-Shou University, Ted.C. Ho, R.S. Lee,
Terry Chen, ITRI and C.H. Lin, Industrial
Development Bureau, MOEA – Taiwan*
- 4 Advances in Technology for Medical Devices (Abstract only) 23
Norman Stockham, TWI, UK

MP-A2: IC PACKAGING

- 5 CIRCONFLEX: a 10 um Thick Flexible Silicon IC Technology for Chip-In-Paper 24-27
Ronald Dekker, Philips Research, Holland
- 6 Hetero System Integration - Challenges and Choices 28-33
M. Jürgen Wolf, Herbert Reichl, FhG-IZM, Germany
- 7 Benefits and Challenges of System Level Integration and Miniaturisation 34-39
Giles Humpston, Tessera, USA
- 8 The future for IC Packaging and Interconnection for Single packages and
Modules 2005 to 2010 and beyond 40-47
Mark Hutton and Francesca Stern, BPA Consulting Ltd, UK
- 9 Plasma Treatment as a Yield and Quality Improving Tool for Wire
Bonding in Advanced Packaging 48-53
Ursula Meyer, March Plasma Systems, Holland

MP-B2: SPECIAL PCB SESSION

- 10 PCBs, the most critical part of the electronic systems reliability chain 54-61
Hans Danielsson, Mikro Elektronik Konsult AB, Sweden
- 11 Lead Free Assembly: A Practical Tool For Laminate Materials Selection 62-73
Erik J. Bergum, David Humby, Polyclad Europe, UK
- 12 High Temperature Lead-Free Soldering Impact on PCB Substrates and Component Packaging 74-81
Vern Solberg, Tessera, USA
- 13 Lead-free Reflow Soldering, a Challenge for PCB Performance 82-88
Markku Jämsä, Aspocomp, Finland
- 14 PCB-Materials and Surfaces for Lead Free Soldering 89-93
Thomas M. Krziwanek, AT&S, Austria

TA-A1: TREND SETTING

- 15 Future RF Components and Modules – Technology Decision is Question No. 1.....94-97
Martin Oppermann, EADS, Germany
- 16 Historic and Future Trends in Miniaturisation of Electronics.....98-103
*Kati Kokko, Tampere University of Technology,
 Paul Collander, Poltronic, Finland*

TA-B1: LEAD-FREE & ENVIRONMENT

- 17 Implementation of Eco Design in the Electronics Sector104-110
Ivan Szendiuch, Brno University of Technology, Czech Republic
- 18 Modified Engelmaier’s Model for Lead-free Solder Materials.....111-116
*Olli Salmela, Tero Nieminen, Jussi Särkkä,
 Markku Tammenmaa, Nokia Networks, Finland*

TA-A2: TREND SETTING

- 19 Overview of Printed Electronics117-121
*Kari Määttänen, Turku Polytechnic, Aulis Tuominen,
 Turku University of Technology, Finland*
- 20 ECPR (ElectroChemical Pattern Replication) – Metal printing for advanced packaging applications122-126
Patrik Möller, Replisaurus, Sweden
- 21 Polymer optical films and packaging of active optical components127
*Jon H. Ulvensøen, Lars Henriksen
 and Morten Eliassen, Ignis, Norway*

TA-B2: PhD SESSION

- 22 Design for Manufacturability and Reliability of Embedded Display Smart Card128-134
*Rui Rodrigues, Yang Liu, Johan Liu,
 SMIT Center, Sweden/China*
- 23 Transfer of Silicon Nitride to Silicon by Fusion Bonding135-138
Kjersti Midtbø, Arne Rønnekleiv, NTNU, Norway
- 24 Factors influencing the surface insulation resistance139-145
*Mats Lindgren, Kitron development/Jönköping University,
 Peter Leisner, Acreo, Sweden*
- 25 Roadmap: Wearable Computers146-154
*Michel Chedid, Saab Training Systems AB,
 Peter Leisner, Acreo, Sweden*
- 26 Modeling and Simulation of Low Pass Filter using RF MEMS Capacitance and Transmission line.....155-159
Shimul Chandra Saha, Trond Sæther, NTNU, Norway

TP-A1: EMBEDDING

- 27 2.4GHz Wireless LAN (WLAN) Module with Embedded Capacitors and
 Balun Using Printed Wiring Board (PWB) Process.....160-164
*Ying-Jiunn Lai, Uei-Ming Jow, Shyi-Ching Liau,
 Chang-Sheng Chen, Chin-Sun Shyu, Chang-Lin Wei,
 Syun Yu, ERSO/ITRI, Taiwan*

- 28 Chip Embedding in Printed Circuit Board Production.....165-171
*Andreas Ostmann, FhG-IZM, Germany,
Arno Kriechbaum, AT&S, Johan De Baets,
IMEC, Hannes Kostner, Datacon*

TP-B1: MEMS & MEMS PACKAGING

- 29 Modelling the behaviour of a MEMS angular rate sensor, with focus on package effects.....172-177
Eskild Westby, Rudolf Krondorfer, Sensoror, Norway

- 30 Microtechnologies to enable Lab-on-a-Chip and Biosensing Technologies
*Erik Johannesen, Microtech Innovation, Norway,
Jon Cooper, University of Glasgow, UK*

- 31 3-D Packaging of MEMS Sensors for Development of Miniaturised Inertial Measurement Unit.....178-182
*Bivragh Majeed, Andrew Lynch, John Barton,
Brendan O'Flynn, Cian O'Mathuna,
Kieran Delaney, Tyndall, Ireland*

TP-A2: 3D

- 32 3D MID –Technology for Moulded Patterned Substrates.....P IC
Minna Arra, Anneli Ojapalo, Perlos, Finland

- 33 Development of High Density Wiring Technology and Interconnect
Technology with Silicon Through-hole.....191-195
*S. Chujo, K. Nakayama, M. Yamaguchi, M. Akazawa,
S. Kuramochi, K.Suzuki, Y. Fukuoka,
Dai Nippon Printing, Japan*

- 34 2.5 to 5 Nanometer Dielectric Films for System in Package (SIP) Applications.....196-202
Ernest Demaray, Young Park, Symmorphix, USA

TP-B2: DEMANDING PACKAGING

- 35 Packaging Techniques for RF MEMS (Abstract only)203
Gabriel M. Rebeiz, University of California, USA

- 36 Packaging issues of 24 GHz traffic control radar front end based on SiGe and LTCC technologies.....204-211
*Jaakko Lenkkeri, Eveliina Juntunen,
VTT Electronics, Finland*

- 37 Reliable electronics packaging for long term 200 °C applications.....212-215
*Froydis Oldervoll, Helge H. Refsum, Truls Fallet,
Frode Strisland, SINTEF, Norway*

PhD- POSTER SESSION

- 38 Design of a three-axis accelerometer for heart motion studies.....216-218
*Craig Lowrie, Christopher Grinde, Lars Hoff,
Marc Desmulliez, MicroSystem Engineering Centre (MISEC),
School of Engineering and Physical Sciences,
Heriot-Watt University, Edinburgh, SCOTLAND
Faculty of Science and Engineering,
Vestfold University College, Horten, NORWAY
Faculty of Mathematics and Natural Sciences,
Oslo University, Oslo, NORWAY*

39 Analytical Microsystems for Biomedical Research	219-221
<i>Erik A. Johannessen, Jon M. Cooper,</i> <i>Microtech Innovation AS, Norway,</i> <i>University of Glasgow, UK</i>	
40 Backing requirements for capacitive micromachined ultrasonic transducer arrays on silicon	222-226
<i>Sigrid Berg, Arne Rønnekleiv, NTNU, Norway</i>	
41 Low-Noise Amplifier Designs at 5 GHz	227-229
<i>Adriana Serban, Shaofang Gong,</i> <i>Linköping University, Sweden</i>	
42 Study of high-speed data transfer utilizing flexible and parallel transmission lines	230-235
<i>Allan Huynh, Shaofang Gong, Linköping University,</i> <i>Leif Odselius, Micronic laser System, Inc., Sweden</i>	
43 Adhesion of photoresist on thinfilm aluminium	236-247
<i>Daniel Tomicic, Acreo, Sweden</i>	
44 Biocompatible packaging of a three-axis micro accelerometer	248-248
<i>K. Imenes, K. Aasmundtveit, L. Hoff, O.J. Elle and</i> <i>E. Fosse, Vestfold University College,</i> <i>Faculty of Science and Engineering, Horten, Norway</i> <i>Rikshospitalet University Hospital, Interventional Centre,</i> <i>Oslo, Norway</i>	